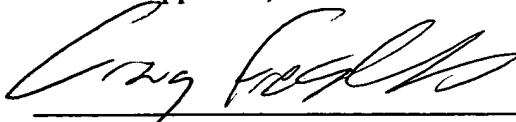


REMARKS

Claims 19-35 are submitted as replacements to claims 3-18 to remove multiple dependencies. No new matter has been added to the application by these amendments, and the application is now ready for examination on the merits. If any questions regarding the application arise, please contact the undersigned attorney. Telephone calls related to this application are welcomed and encouraged. The Commissioner is authorized to charge any fees or credit any overpayments relating to this application to deposit account number 18-2055.

For the Applicant,



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): RAMSEY et al.

Atty. Docket: 78104.025

Title: PROCESS FOR DEPOSITING CONDUCTING LAYER ON SUBSTRATE

**AMENDMENT SHEET ("MARKED-UP" COPY)
SHOWING CHANGES TO APPLICATION
(37 CFR §§1.121(b)(1)(iii); (c)(i)(ii))
(To Accompany Preliminary Amendment)**

In accordance with 37 CFR §§1.121(b)(iii) and (c)(ii), following are the amendments made to the specification and/or claims of the above-noted application.

- All deletions are indicated by brackets [like so] and all additions are indicated by underlining like so.
- The additions and deletions are made with respect to the application as it is understood to exist prior to entry of this amendment (i.e., any amendments are made with respect to the previous version).
- While 37 CFR §§1.121(b)(1)(iii) and (c)(1)(ii) does not require that new and canceled paragraphs and claims be supplied on this "marked-up" copy, such new additions and cancellations are nevertheless provided below to aid the reviewer's understanding.

IN THE SPECIFICATION:

The following paragraph is added between lines 1-2 at page 1 of the specification.

- FIELD OF THE INVENTION -

The following paragraph is added between lines 5-6 at page 1 of the specification.

- BACKGROUND OF THE INVENTION -

The following paragraph is added between lines 27-28 at page 2 of the specification.

- SUMMARY OF THE INVENTION -

The following paragraph is added between lines 5-6 at page 7 of the specification.

- DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS OF THE INVENTION-

IN THE CLAIMS:

Claims 3-18 are canceled without prejudice to further prosecution of these claims in one or more continuing applications.

Claims 19-35 are added as follows:

19. [NEW] The process of claim 2 further comprising the step of attaching an electrical component to the first or second conducting layer by means of a conductive polymer adhesive.
20. [NEW] The process of claim 1 wherein the substrate is formed from a polymer into a flexible sheet.
21. [NEW] The process of claim 1 wherein the substrate is coated with a copolymer adhesive.
22. [NEW] The process of claim 1 wherein the ink comprises a particulate material suspended in a mixture of a resin and an organic solvent.
23. [NEW] The process of claim 22 wherein the particulate material is a metal or carbon.
24. [NEW] The process of claim 22 wherein the resin is a polymer having amide groups.
25. [NEW] The process of claim 1 wherein the thickness of the seeding layer is from 3 to 5 microns.
26. [NEW] The process of claim 1 wherein the thickness of the first electrically conducting layer is less than or equal to 4 microns.
27. [NEW] The process of claim 1 wherein the thickness of the first electrically conducting layer is about 0.25 microns.
28. [NEW] The process of claim 1 wherein the first electrically conducting layer is formed from at least one of copper, palladium, silver, gold, platinum, and nickel.
29. [NEW] The process of claim 1 further comprising the step of soldering an electrical component on the substrate.
30. [NEW] The process of claim 1 further comprising the step of attaching an electrical component to the first conducting layer by means of a conductive polymer adhesive.
31. [NEW] An electrical assembly comprising a substrate having at least one electrically conducting layer, which layer has been formed by the process of claim 1.
32. [NEW] An interconnect for a battery, the interconnect being formed by the process of claim 1.

33. [NEW] A battery containing the interconnect of claim 32.
34. [NEW] A lithographic ink for use in a lithographic printing process onto a polymer substrate, the ink comprising a particulate material suspended in a mixture of a resin and an organic solvent, wherein the resin comprises a polyamide.
35. [NEW] An ink as claimed in claim 34 wherein the particulate material is a metal or carbon.

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